

Docket No.: 3008-0028  
File No. 521.41457X00  
Client No.: PHCF-01094



PATENT

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of

Seigi AOYAMA et al.

Application S/N 09/892,630

Filed: June 28, 2001

: Art Unit: 2827

: Examiner: T. Dinh

For: LEAD-FREE SOLDER, AND CONNECTION LEAD AND ELECTRICAL COMPONENT  
USING SAID LEAD-FREE SOLDER

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**REQUEST FOR APPROVAL OF DRAWING AMENDMENT**

Assistant Commissioner of Patents  
Washington, D.C. 20231

Sir:

Approval of the changes to Figure(s)6, 7A and 7B as shown on the attached photocopies, is courteously solicited. A copy of these Figure(s) with the changes marked in red is also attached.

Respectfully submitted,

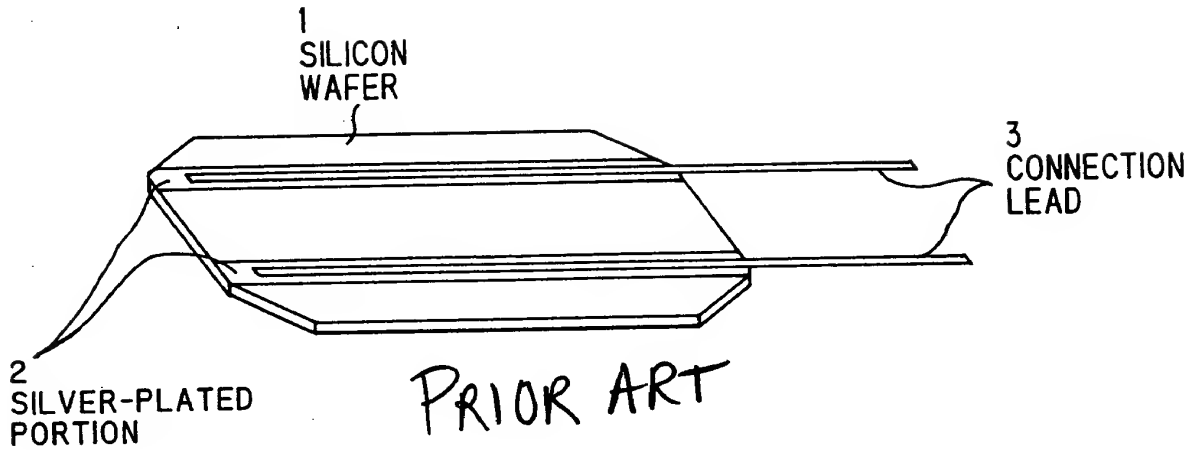
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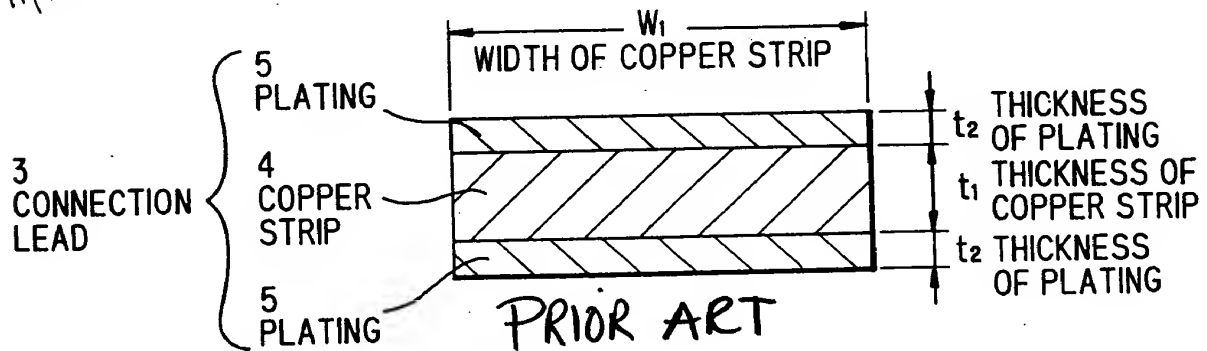


4/4  
**FIG. 6**

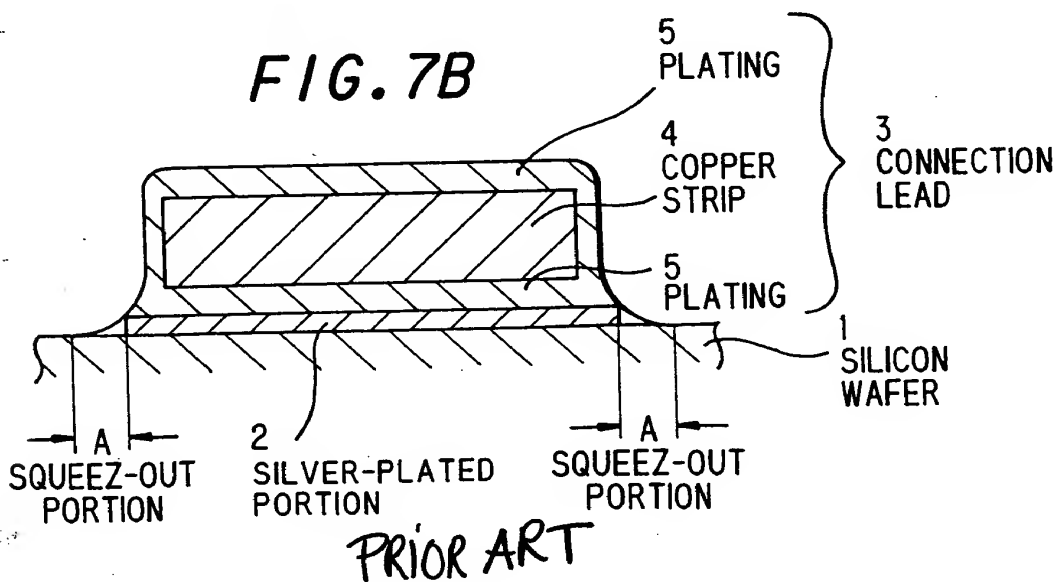


OK  
FD  
11/14/02

**FIG. 7A**

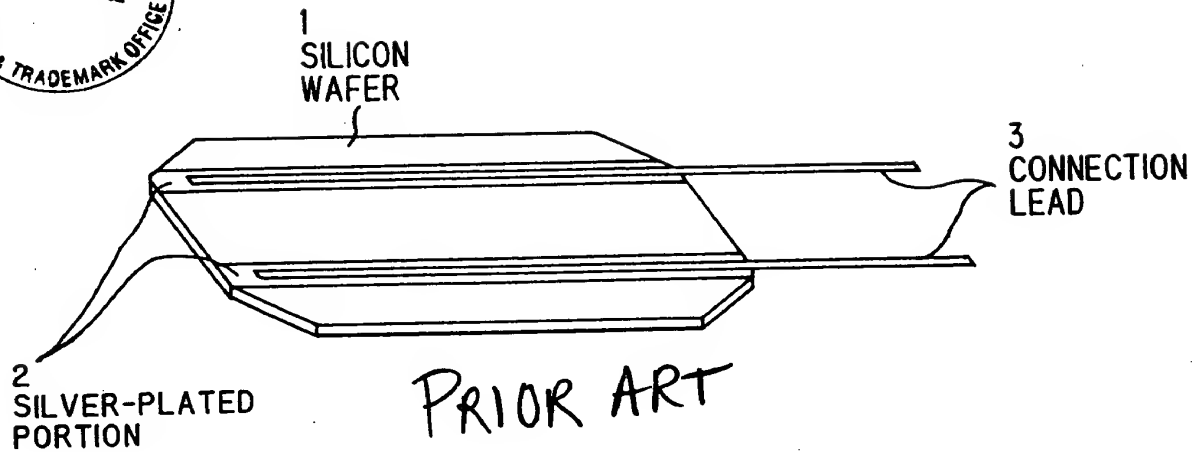


**FIG. 7B**

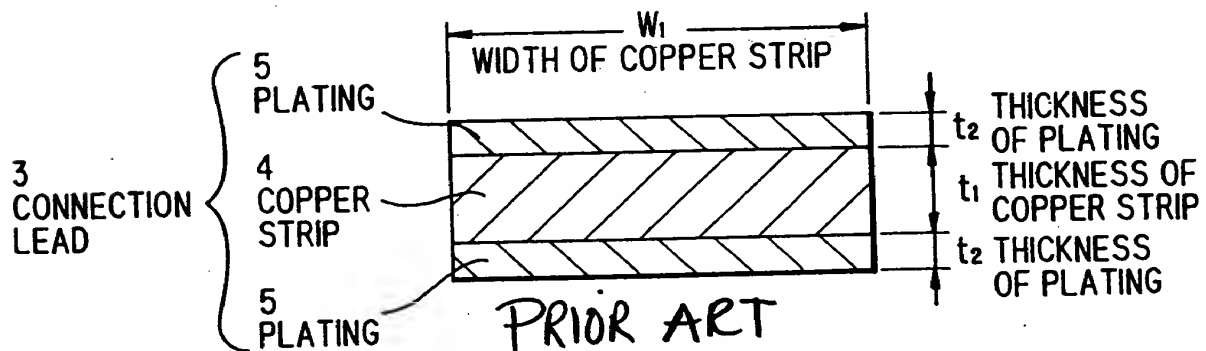




4/4  
**FIG. 6**



**FIG. 7A**



**FIG. 7B**

